

Patent Abstracts of Japan

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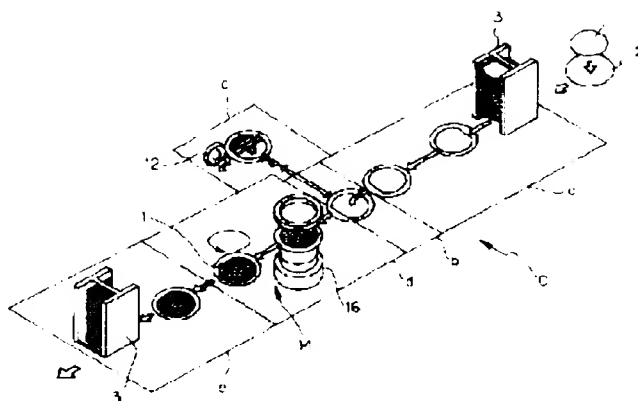
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TITLE : CLEANING METHOD AND APPARATUS FOR WAFER



ABSTRACT : PURPOSE: To provide a cleaning method and apparatus with good efficiency in cleaning for a diced piece after a wafer is diced.

CONSTITUTION: A wafer 1 is stuck to a dicing sheet 2, and cut into a plurality of diced pieces by using a dicing saw. In a dicing sheet stretching apparatus 16, the outer boundary part of the dicing sheet 2 is pulled outward in an annular shape between a ring and push-up stage to space out the diced pieces, and in this state the wafer 1 on the dicing sheet 2 is washed. Cleaning water is fed to the diced face and an effect in cleaning to this place can be improved. The push-up stage may have an inner heater so that the heated sheet can be more extended in space.

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